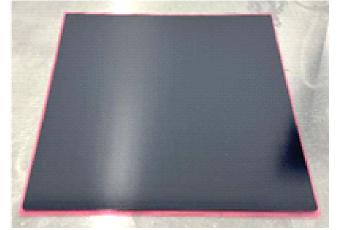
Materials for Power Devices and Electronic

Molding Compounds

NAGASE | Delivering next.

Molding Compounds for Next-Generation Power Devices

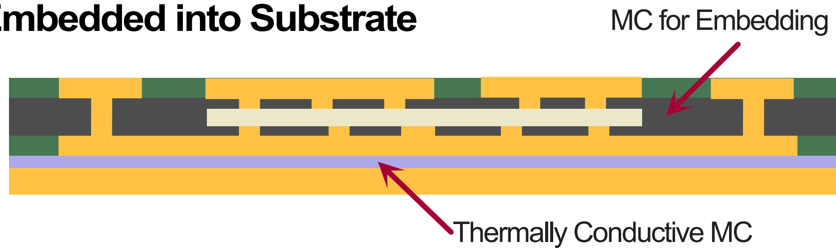
New Molding Compound Concept



Features

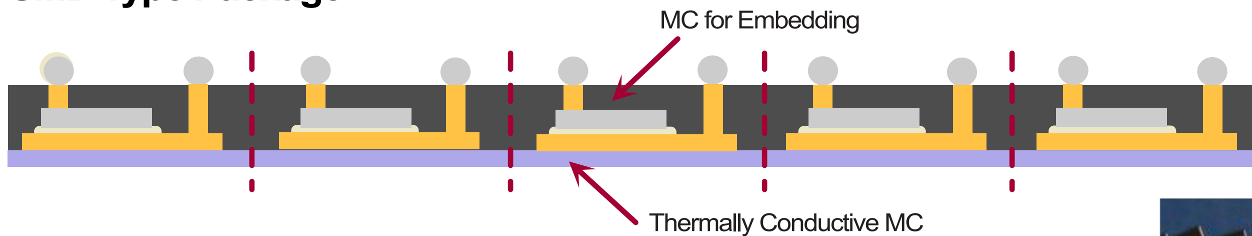
» Leads to low electrical loss & low inductance
» Extremely good embedding performance
» High thermal reliability

Power Dies Embedded into Substrate



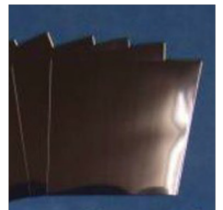
» Die Embedding through Mold Compound with high reliability
» Process: Compression, Laminating, Pressing

BGA / SMD Type Package



» BGA type small Package for SMT
» Process: WLP / PLP by compression

LMC
(Liquid Molding Compound)



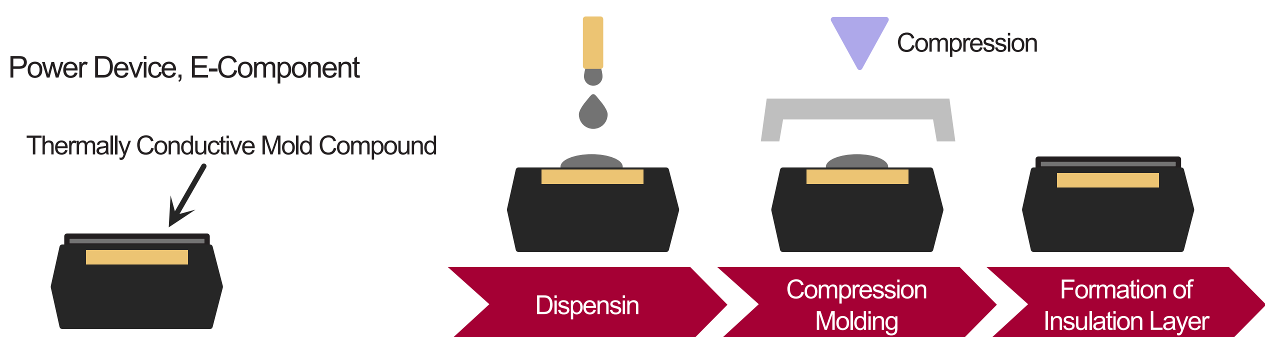
Rigid Thermally Conductive Layer by Mold Method

High Thermal Conductive Liquid Mold Compound

Features

» Leads to robust thermal conductivity & insulation layer
» a-SMC: High thermal conductivity up to 10 W/mK
» LMC: easily controllable by dispensing machine

A-SMC
(Advanced Sheet Molding Compound)



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